## **INFORMATION NOTE**



#### N° 031/17

Dear Customer,

With this INFINEON Technologies Information Note we would like to inform you about the following

Introduction of a modified packing affecting HybridPACK<sup>™</sup> 2 modules

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## **INFORMATION NOTE**



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Products affected:	Sales Name	SP N°	OPN	
	FS400R12A2T4	SP000917120	FS400R12A2T4BOSA1	
	FS600R07A2E3	SP000555680	FS600R07A2E3BOSA1	
	FS600R07A2E3	SP001240888	FS600R07A2E3BOSA3	
	FS600R07A2E3_B31	SP001064606	FS600R07A2E3B31BOSA1	
	FS600R07A2E3_B32	SP001240870	FS600R07A2E3B32BOSA1	
	FS675R08A2P2_B31	SP001359426	FS675R08A2P2B31BOSA1	
	FS800R07A2E3	SP000913148	FS800R07A2E3BOSA2	
	FS800R07A2E3	SP001240900	FS800R07A2E3BOSA4	
	FS800R07A2E3_B31	SP001064622	FS800R07A2E3B31BOSA1	
	FS800R07A2E3_B32	SP001240894	FS800R07A2E3B32BOSA1	
	FS900R08A2P2_B31	SP001232072	FS900R08A2P2B31BOSA1	

### Detailed Change Information:

Subject:	Introduction of a modified packing affecting HybridPACK <sup>™</sup> 2 modules.		
Reason:	Due to continuous improvement.		
Description:	<u>Old</u>	New	
	<ul> <li>Please refer to 3_cip17031 attached.</li> </ul>		
Product Identification:	Product can be identified due to change in visual appearance of packing.		
Impact of Change:	No changes in form, fit or function of the product.		
► Attachments:	Additional information: 3_cip17031		
Intended start of delivery:	From July 2017 onwards.		

If you have any questions, please do not hesitate to contact your local Sales office.

## Introduction of a modified packing affecting HybridPACK<sup>™</sup> 2 modules

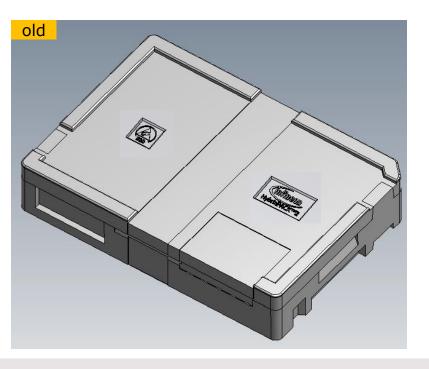
Customer information package Info Note 031/17

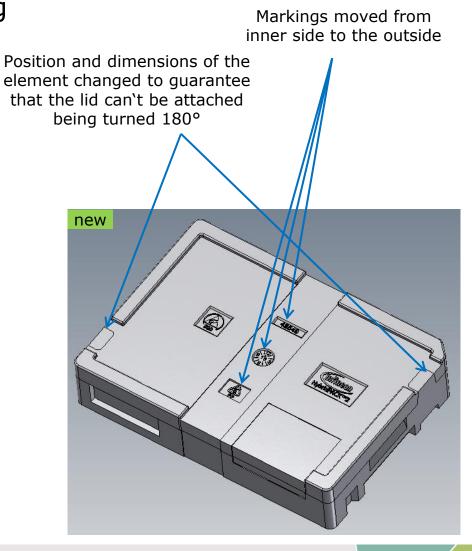


restricted



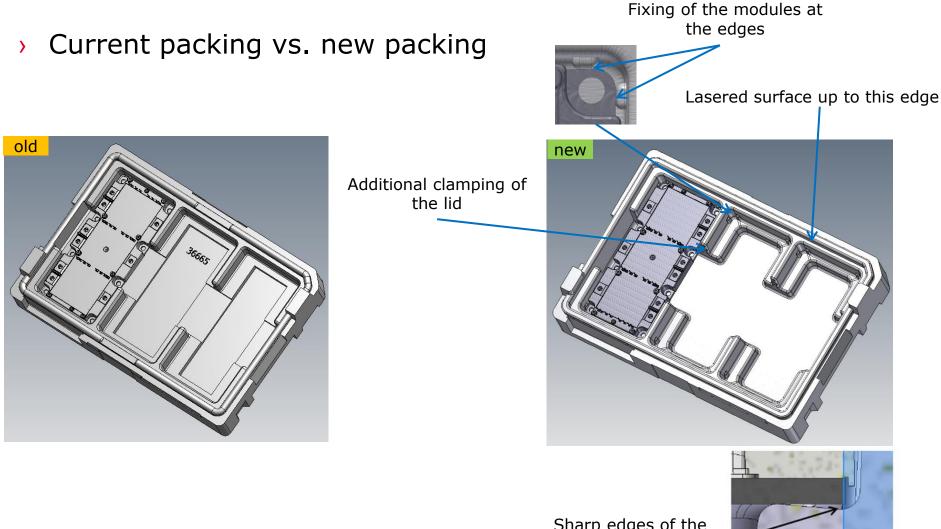
> Current packing vs. new packing





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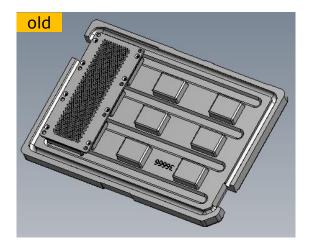


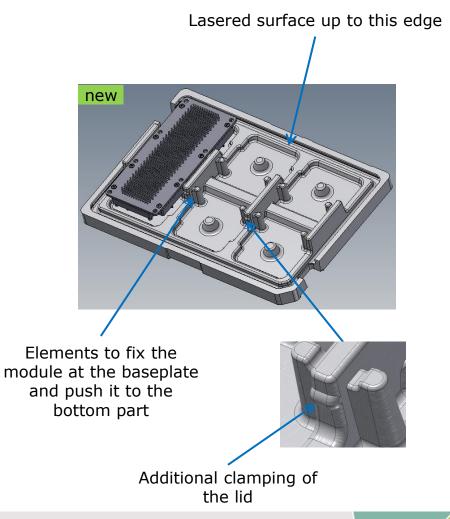


Sharp edges of the baseplate have no contact to the packing



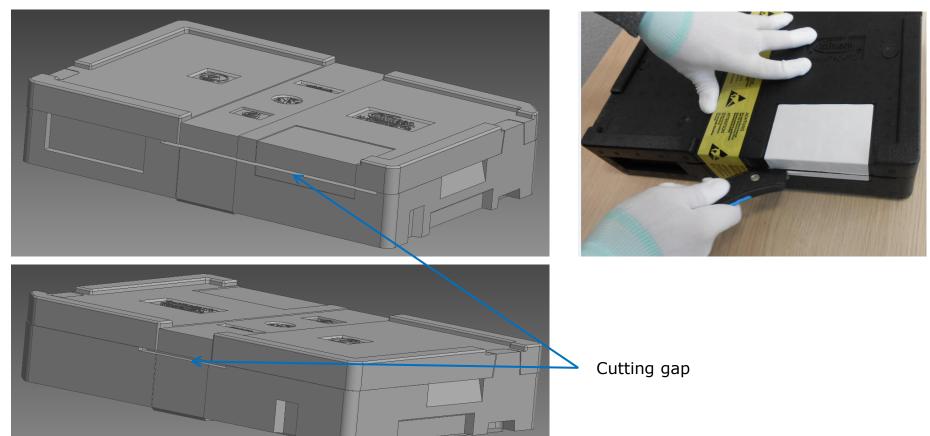
Current packing vs. new packing







- > Current packing vs. new packing
  - New packing got a defined cutting gap



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